

10 C1 in a second phase effecting a connection of the wire conductor to the terminal area with a connecting instrument and [a] the wire conductor is connected extending in parallel to the surface plane of the windings of [he] the wire coil.

Please amend claim 53 as follows.

C2 14/ 53. (Amended) The process according to claim 40, wherein a rotationally symmetrical coil is formed with a wire conductor wired on a substrate taking the form of a winding support and rotating relative to [the] a wiring device.

Please add the following new claims:

sub D2 79. A process for arranging a wire conductor on a substrate to form a wire coil connected to a chip unit, the process comprising the steps of:

providing the substrate with a recess for receiving the chip unit;

inserting the chip unit into said recess;

5 guiding the wire conductor over said recess and away from said recess with a wire guiding device;

subsequently fixing the wire conductor to the substrate by ultrasonically vibrating the wire guiding device and the wire conductor during said fixing, said guiding and said fixing including forming the wire coil from the wire conductor;

10 subsequently connecting the wire conductor to a terminal area of the chip unit with the wire conductor connected to the terminal area extending in parallel to the surface plane of the